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14. The method of claim 1, wherein,
 at least a portion of the at least one epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer proximate to the substrate is patterned;
 and
 at least a portion of the at least one epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer distal to the substrate is coalesced or continuous and relaxed, having a strain, relative to fully-relaxed $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$, of less than 0.01%. 5
15. The method of claim 1, wherein the at least one $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer comprises more than one epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer, wherein 10
 at least a portion of a first epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer overlying the substrate is patterned; and
 at least a portion of a second epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer overlying the first epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer is coalesced or continuous and relaxed, having a strain, relative to fully-relaxed $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$, of less than 0.01%. 15
16. The method of claim 1, wherein at least one of x and y is between 0.01 and 0.50.
17. A device comprising a biaxially relaxed epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer formed by the method of claim 1, wherein the epitaxial $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$ layer is characterized by: 20
 $0 \leq x, y, x+y \leq 1$ and $y > 0.10$;
 a surface orientation within 5 degrees of a c-plane;
 a thickness greater than 100 nanometer;
 a concentration of threading dislocations less than 10^8 cm^{-2} ; and
 a biaxial strain less than 0.1%. 25

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18. A device, comprising at least one layer comprising $\text{Al}_x\text{In}_y\text{Ga}_{(1-x-y)}\text{N}$, wherein the at least one layer is characterized by:
 $0 \leq x, y, x+y \leq 1$ and $y > 0.10$;
 a surface orientation within 5 degrees of a c-plane;
 a thickness greater than 100 nanometer;
 a concentration of threading dislocations less than 10^8 cm^{-2} ; and
 a biaxial strain less than 0.1%.
19. The device of claim 18 wherein the device is selected from among a light emitting diode, a laser diode, a photodetector, an avalanche photodiode, a transistor, a rectifier, and a thyristor; one of a transistor, a rectifier, a Schottky rectifier, a thyristor, a p-i-n diode, a metal-semiconductor-metal diode, high-electron mobility transistor, a metal semiconductor field effect transistor, a metal oxide field effect transistor, a power metal oxide semiconductor field effect transistor, a power metal insulator semiconductor field effect transistor, a bipolar junction transistor, a metal insulator field effect transistor, a heterojunction bipolar transistor, a power insulated gate bipolar transistor, a power vertical junction field effect transistor, a cascode switch, an inner sub-band emitter, a quantum well infrared photodetector, a quantum dot infrared photodetector, a solar cell, and a diode for photoelectrochemical water splitting and hydrogen generation.

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